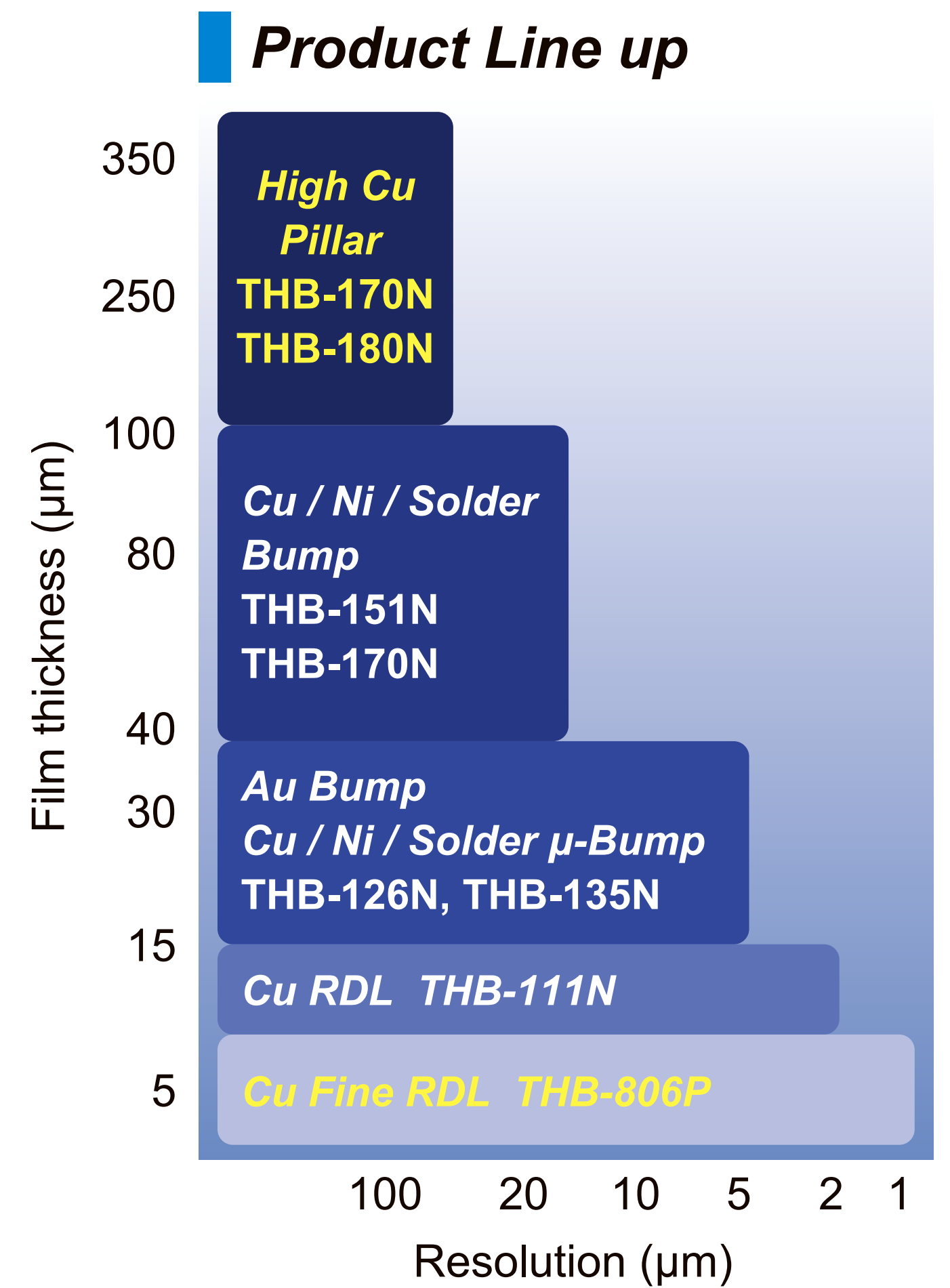
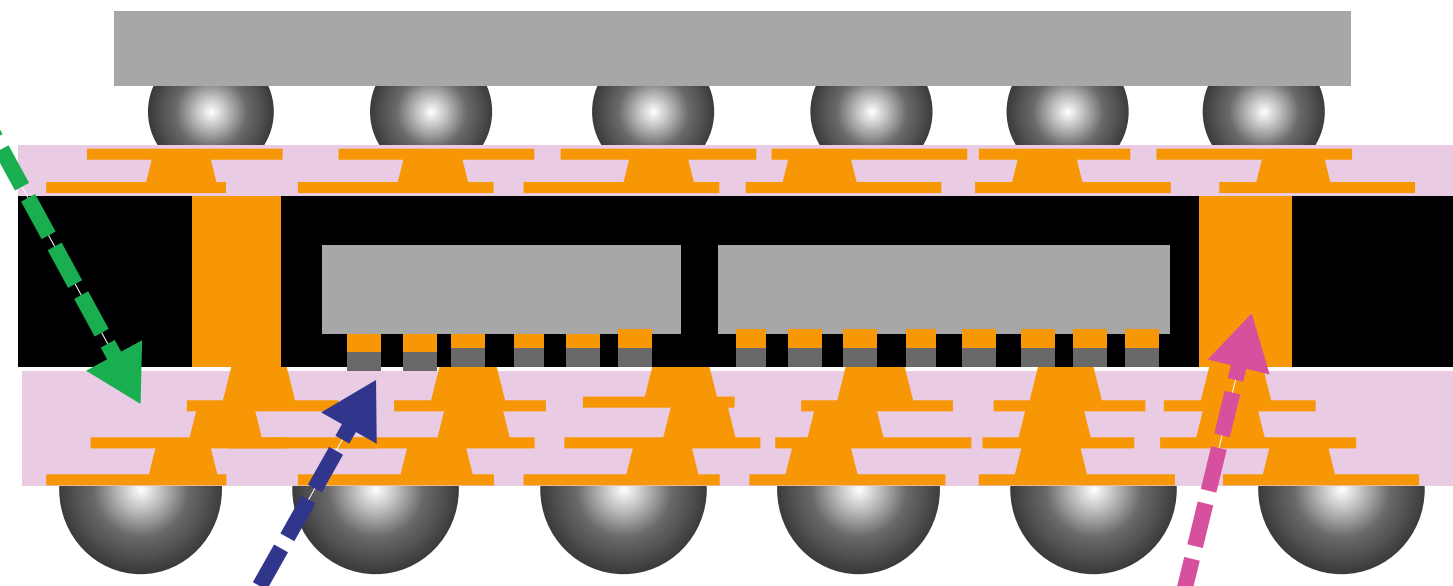


JSR ELPAC™ THB™ series Thick Layer Photoresist For Plating

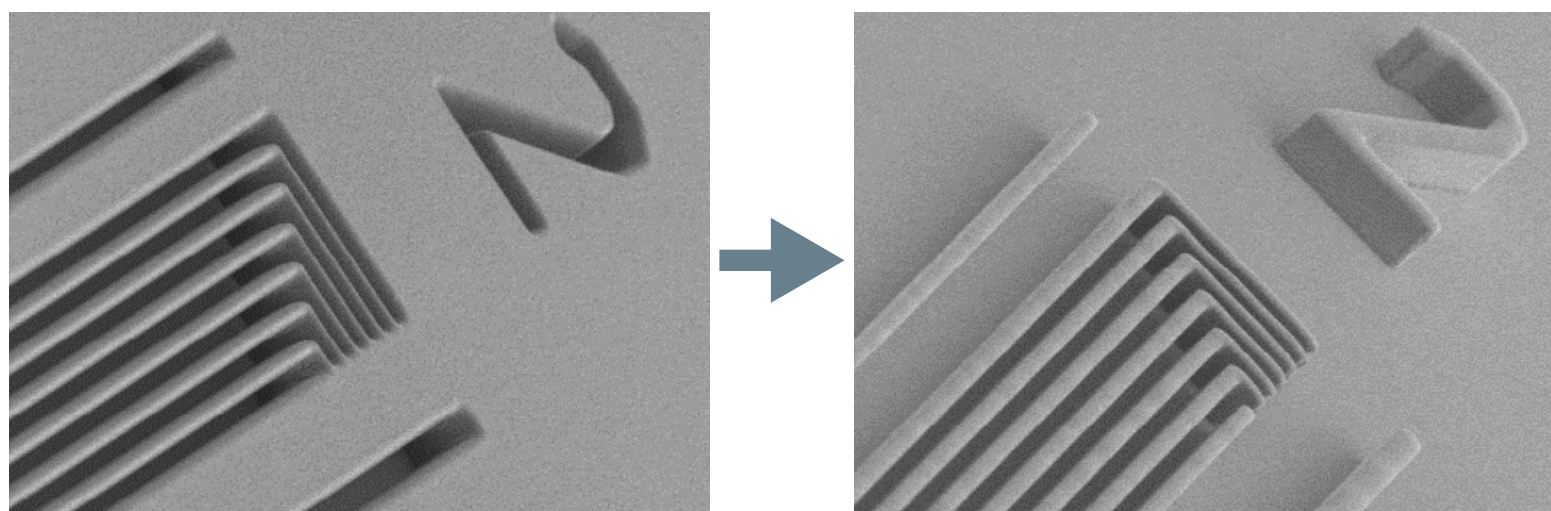
RDL / Fine RDL
FT : 5~15 μm
Plating : Cu

C4 / μ -Bump
FT : 20~100 μm
Plating : Cu / Ni / SnAg

High Cu pillar
FT : >100 μm
Plating : Cu



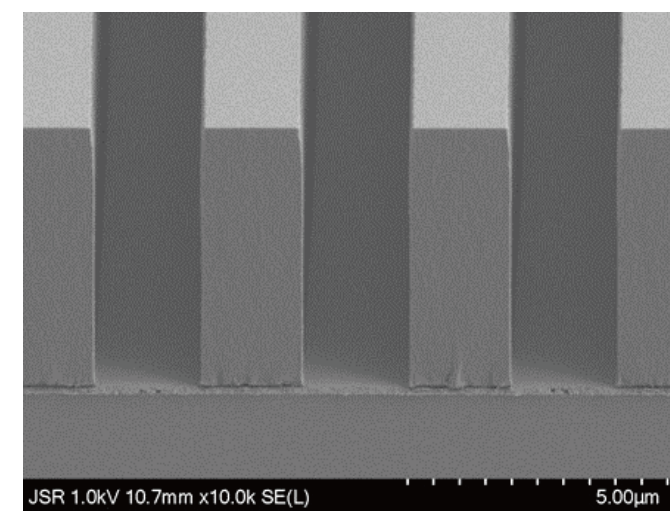
Cu RDL Negative Tone



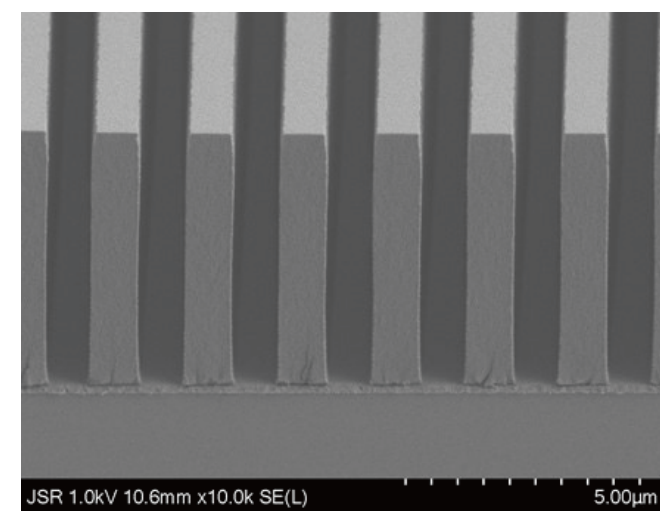
Cu Plate
THB Stripped

Cu Fine RDL Positive Tone

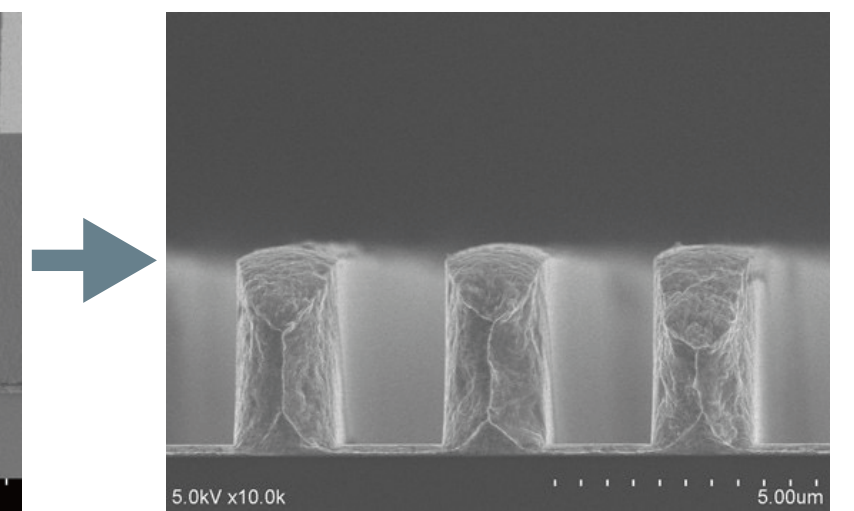
2.0 μm L/S



0.9 μm L/S

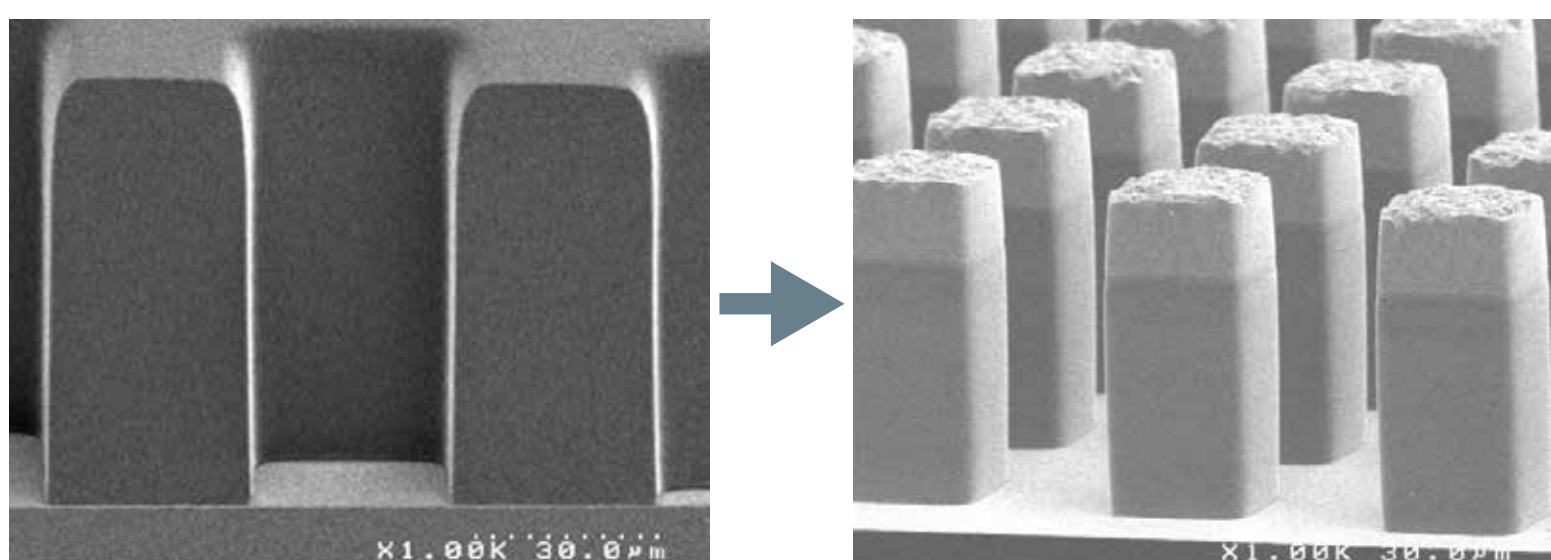


Film Thickness: 5 μm



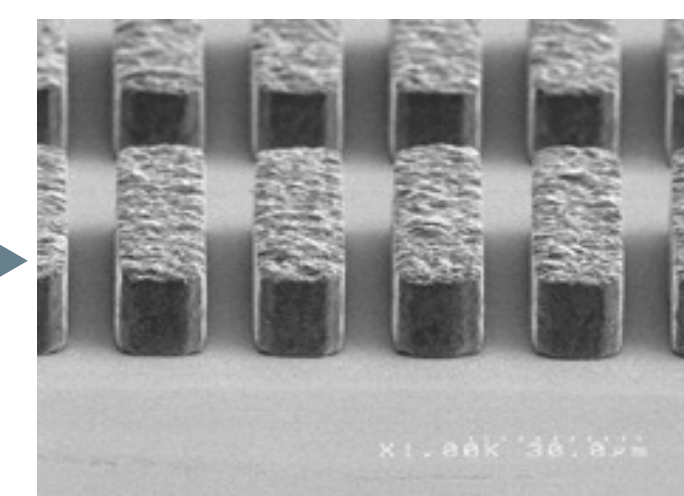
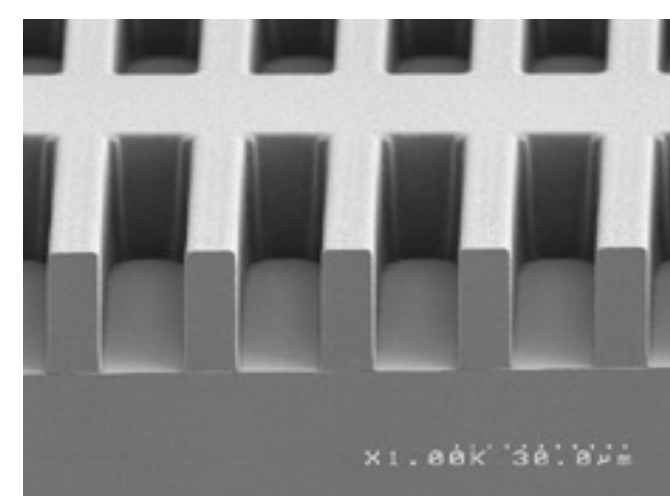
Cu Plate
THB Stripped

Cu / Ni / Solder Bump

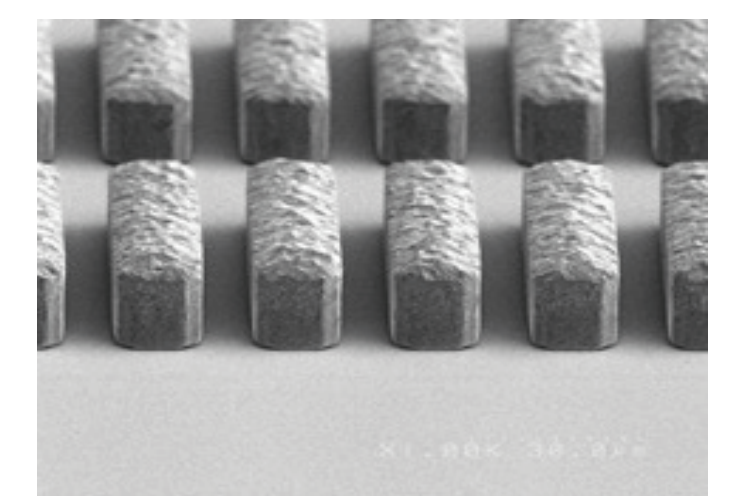


Cu / Ni / SnAg Plate
THB Stripped

Au Bump



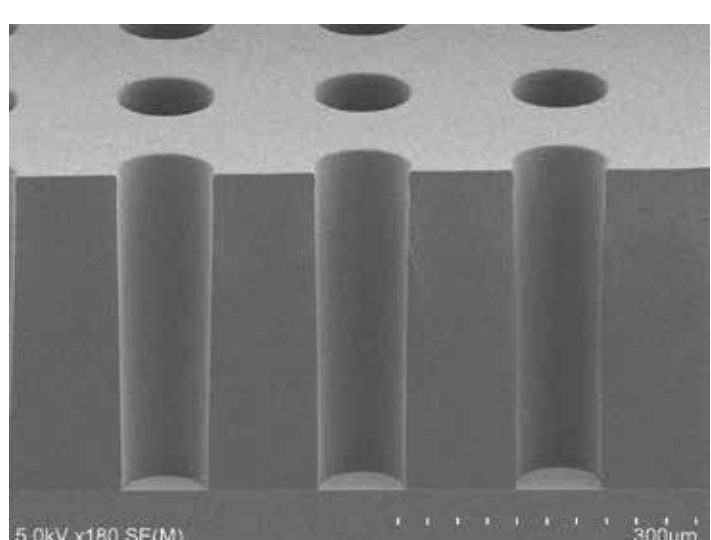
Cyanide Au Plate
THB Stripped



Non-cyanide Au Plate
THB Stripped

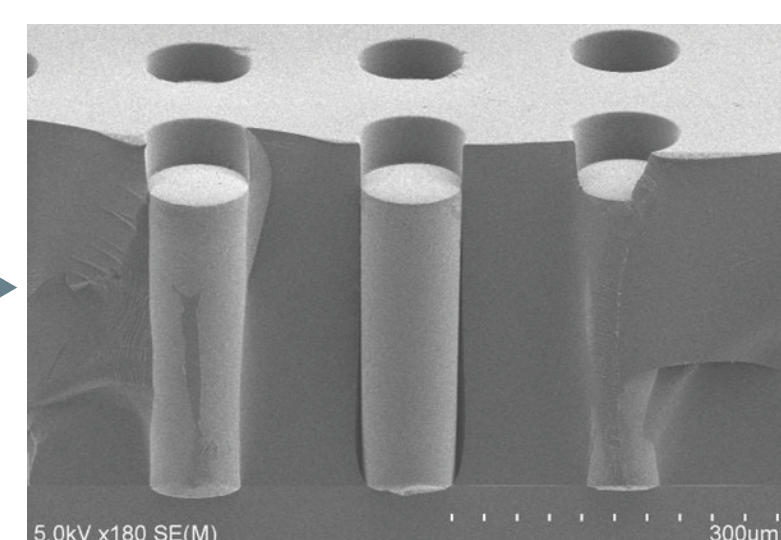
High Cu Pillar

After Development



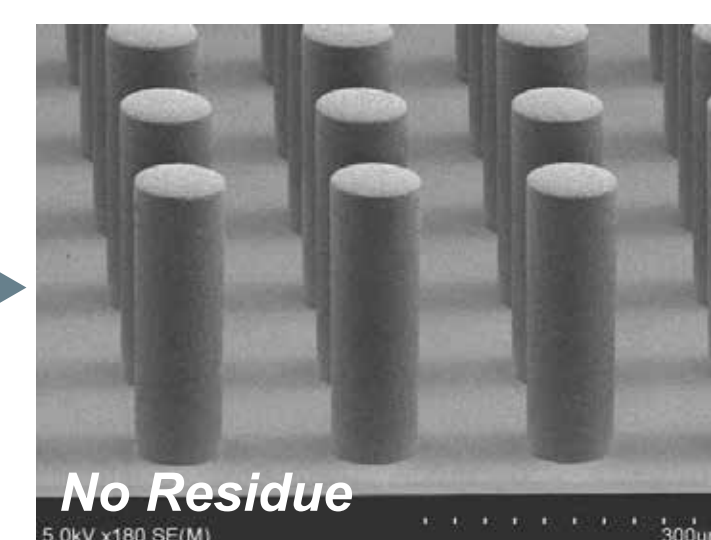
Film Thickness
340 μm / 100 μm ϕ

After Cu Plating



Cu Height 290 μm
w/ Cu Plating Chemical from Ishihara Chemical

After Stripping



No Residue

